



For Reference Only; not for tooling use
(reference DWG-0000378, Rev. 3)
Dimensions in millimeters
Exact case and lead configuration at supplier discretion within limits shown

- A** Terminal #1 mark area
- B** Exposed thermal pad (reference only, terminal #1 identifier appearance at supplier discretion)
- C** Reference land pattern layout (reference IPC7351 QFN50P500X500X100-29V1M); All pads a minimum of 0.20 mm from all adjacent pads; adjust as necessary to meet application process requirements and PCB layout tolerances; when mounting on a multilayer PCB, thermal vias at the exposed thermal pad land can improve thermal dissipation (reference EIA/JEDEC Standard JESD51-5)
- D** Coplanarity includes exposed thermal pad and terminals
- E** Branding scale and appearance at supplier discretion

Standard Branding Reference View 1
Line 1: Part Number
Line 2: Logo A, 4-Digit Date Code
Line 3: Characters 5, 6, 7, 8 of Assembly Lot Number

Standard Branding Reference View 2
Line 1: Part Number
Line 2: Logo A, 4-Digit Date Code
Line 3: Characters 5, 6, 7, 8 of Assembly Lot Number